



950 Rittenhouse Rd., Norristown, PA 19403 • Tel.: 215/666-7950 • TLX 846-100 MOSTECHGY VAFG

## 2332 STATIC READ ONLY MEMORY (4096x8)

### DESCRIPTION

The 2332 high performance read only memory is organized 4096 words by 8 bits with access times of less than 350 ns. This ROM is designed to be compatible with all microprocessor and similar applications where high performance, large bit storage and simple interfacing are important design considerations. This device offers TTL input and output levels.

The 2332 operates totally asynchronously. No clock input is required. The two programmable chip select inputs allow four 32K ROMS to be OR-tied without external decoding.

Designed to replace two 2716 16K EPROMS, the 2332 can eliminate the need to redesign printed circuit boards for volume mask programmed ROMS after prototyping with EPROMS.

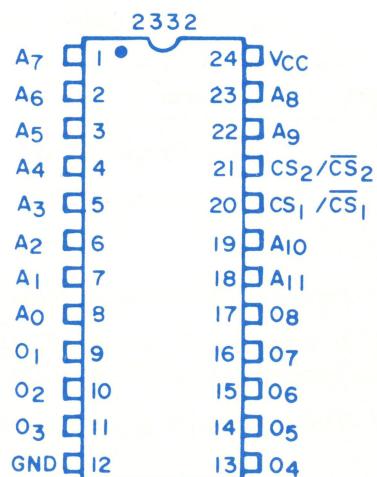
- 4096 x 8 Bit Organization
- Single +5 Volt Supply
- Access Time — 2332 450 ns  
2332A 350 ns
- Completely TTL Compatible
- Totally Static Operation
- Three-State Outputs for Wire-OR Expansion
- Two Programmable Chip Selects
- Pin Compatible with 2716 & 2732 EPROM
- Replacement for Two 2716s
- 2708/2716 EPROMS Accepted as Program Data Inputs
- 400mV Noise Immunity on Inputs

### ORDERING INFORMATION:

Part Number*	Package Type	Access Time	Temperature Range
MPS2332	Molded	450 ns	0°C to +70°C
MPS2332A	Molded	350 ns	0°C to +70°C
MCS2332	Ceramic	450ns	0°C to +70°C
MCS2332A	Ceramic	350ns	0°C to +70°C

\*Final Part Number will be assigned by manufacturer

### PIN CONFIGURATION



## ABSOLUTE MAXIMUM RATINGS

Ambient Operating Temperature	0° to +70°C
Storage Temperature	-65°C to +150°C
Supply Voltage to Ground Potential	-0.5V to +7.0V
Applied Output Voltage	-0.5V to +7.0V
Applied Input Voltage	-0.5V to +7.0V
Power Dissipation	1.0W

## COMMENT

Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

## D.C. CHARACTERISTICS

$T_A = 0^\circ\text{C}$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 5.0\text{V} \pm 5\%$  (unless otherwise specified)

Symbol	Parameter	Min.	Max.	Units	Test Conditions
$I_{CC1}$	Power Supply Current		125	mA	$V_{IN} = V_{CC}$ , $V_O = \text{Open}$ , $T_A = 0^\circ\text{C}$
$I_{CC2}$	Power Supply Current		120	mA	$V_{IN} = V_{CC}$ , $V_O = \text{Open}$ , $T_A = 25^\circ\text{C}$
$I_O$	Output Leakage Current		10	$\mu\text{A}$	Chip Deselected, $V_O = 0$ to $V_{CC}$
$I_I$	Input Load Current		10	$\mu\text{A}$	$V_{CC} = \text{Max. } V_{IN} = 0$ to $V_{CC}$
$V_{OL}$	Output Low Voltage		0.4	Volts	$V_{CC} = \text{Min. } I_{OL} = 2.1\text{mA}$
$V_{OH}$	Output High Voltage	2.4		Volts	$V_{CC} = \text{Min. } I_{OH} = -400\mu\text{A}$
$V_{IL}$	Input Low Voltage	-0.5	0.8	Volts	
$V_{IH}$	Input High Voltage	2.0	$V_{CC} + 1$	Volts	See note 1

## A. C. CHARACTERISTICS

$T_A = 0^\circ\text{C}$  to  $+70^\circ\text{C}$ ,  $V_{CC} = 5.0\text{V} \pm 5\%$  (unless otherwise specified)

Symbol	Parameter	2332		2332A		Units	Test Conditions
		Min.	Max.	Min.	Max.		
$t_{ACC}$	Address Access Time		450		350	ns	
$t_{CO}$	Chip Select Delay		200		200	ns	
$t_{DF}$	Chip Deselect Delay		175		175	ns	
$t_{OH}$	Previous Data Valid After Address Change Delay	40		40		ns	See Note 2

## CAPACITANCE

$T_A = 25^\circ\text{C}$ ,  $f = 1.0\text{MHz}$ , See Note 3

Symbol	Parameter	Min.	Max.	Units	Test Conditions
$C_{IN}$	Input Capacitance		8	pF	All Pins except Pin under Test Tied to AC Ground
$C_{OUT}$	Output Capacitance		10	pF	

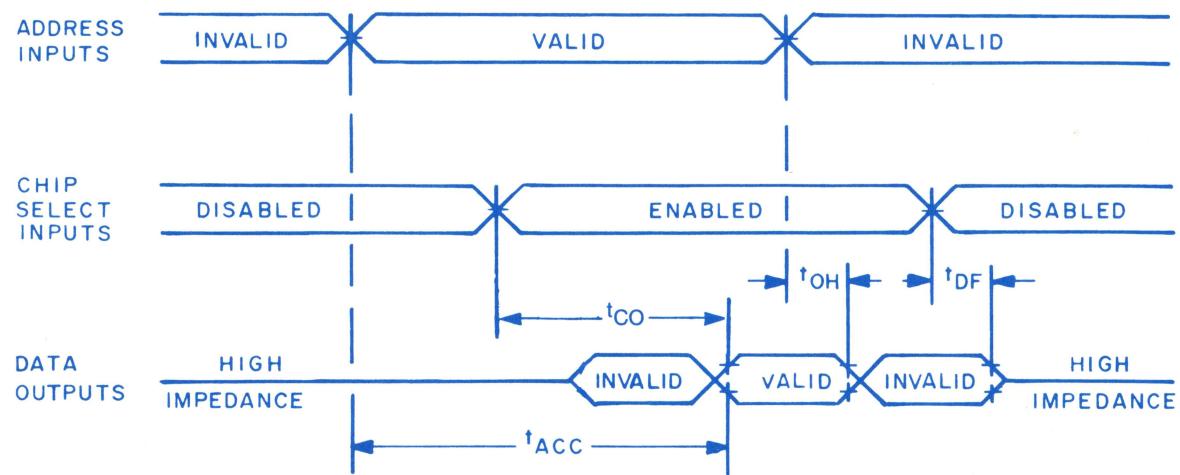
Note 1: Input levels that swing more negative than  $-0.5\text{V}$  will be clamped and may cause damage to the device.

Note 2: Loading 1 TTL + 100 pF, input transition time: 20 ns.

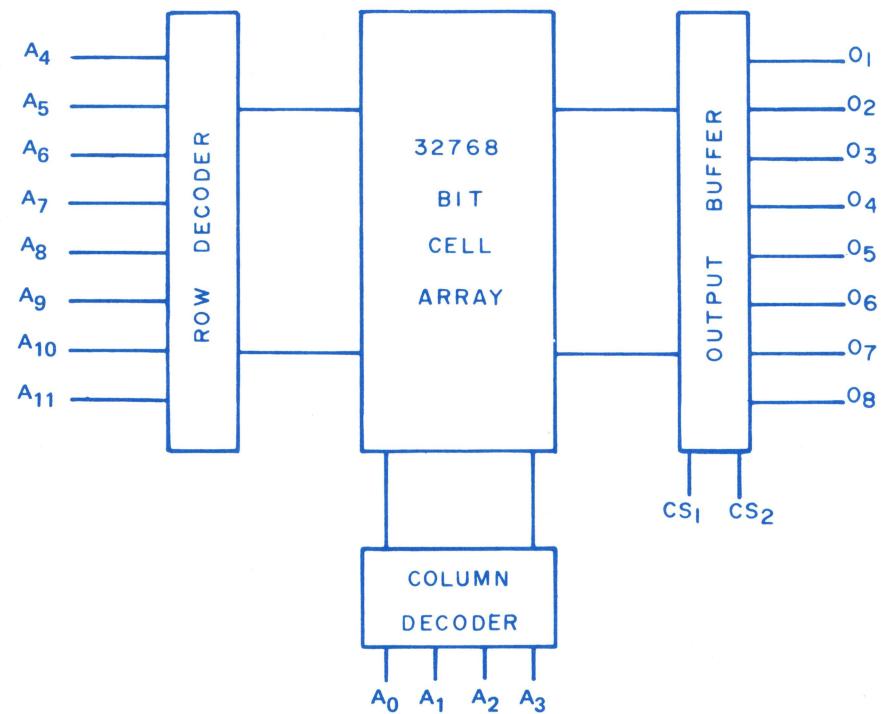
Timing measurement levels: input 1.5V, output 0.8V and 2.0V.  $C_L = 100\text{ pF}$ .

Note 3: This parameter is periodically sampled and is not 100% tested.

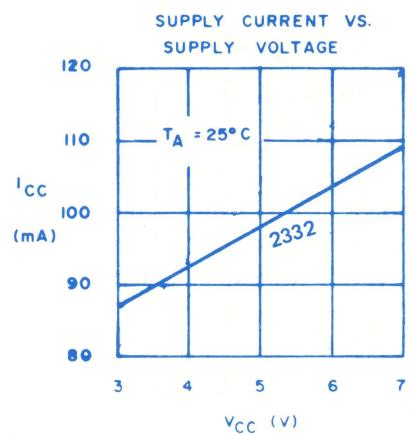
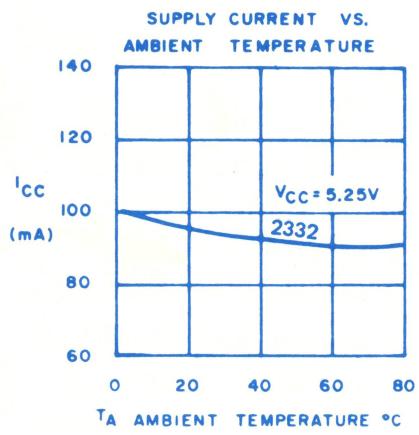
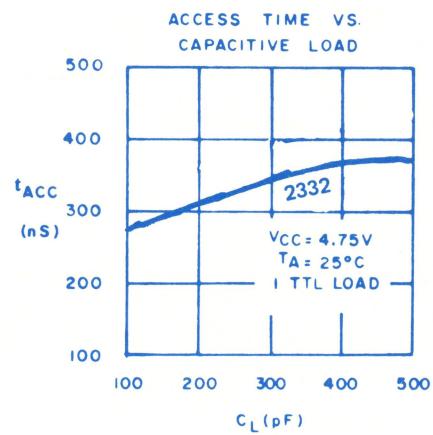
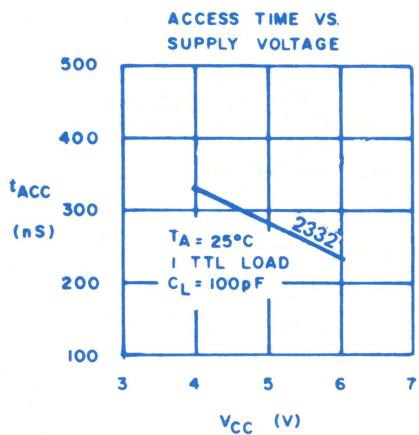
**TIMING DIAGRAM**



**BLOCK DIAGRAM**



## TYPICAL CHARACTERISTICS



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